

Product Compliance Declaration

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Information					
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com		
Part Inform	ation				
Part Number	0346910121	Part Weight	6.28G		
Part Name	STAC64 RA HDR 12 CKT GRY POL B TRAY				

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
STAC64 RA HDR 12 CKT GRY POL B TRAY	Assembly		100	6.28
STAC64 RA HDR HOUSING 12 CKT GRY POL B	Component		77.4045	4.861
PS-ST GF30	Material		77.4045	4.861
PS-ST	Substance		45.4267	2.852799
GF-Fibre	Substance		23.1246	1.452224
Pigment portion, not to declare	Substance	system	0.9482	0.059547
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	5.2684	0.330854
Further Additives, not to declare	Substance	system	2.6366	0.165575
0.64 X 34.93 SQ PIN BRASS REFLOW SN	Component		11.9427	0.75
SQ WIRE C26000 PL 0.625 X 0.625	Material		11.9427	0.75
Cartridge Brass 70% Unplated	Material		11.6974	0.734595
Copper	Substance	7440-50-8	8.1882	0.514217
Zinc (metal)	Substance	7440-66-6	3.5092	0.220379

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Copper Plating	Material		0.0234	0.001472
Copper	Substance	7440-50-8	0.0234	0.001472
Tin Plating	Material		0.1281	0.008047
Tin	Substance	7440-31-5	0.1281	0.008047
Nickel Plating	Material		0.0937	0.005887
Nickel	Substance	7440-02-0	0.0937	0.005886
Further Additives, not to declare	Substance	system	9E-06	6E-07
0.64 X 29.86 SQ PIN BRASS REFLOW SN	Component		9.4586	0.594
SQ WIRE C26000 PL 0.625 X 0.625	Material		9.4586	0.594
Cartridge Brass 70% Unplated	Material		9.2643	0.581799
Copper	Substance	7440-50-8	6.485	0.407259
Zinc (metal)	Substance	7440-66-6	2.7793	0.17454
Copper Plating	Material		0.0186	0.001165
Copper	Substance	7440-50-8	0.0186	0.001165
Tin Plating	Material		0.1015	0.006373
Tin	Substance	7440-31-5	0.1015	0.006373
Nickel Plating	Material		0.0742	0.004662
Nickel	Substance	7440-02-0	0.0742	0.004662
Further Additives, not to declare	Substance	system	7E-06	5E-07
PIN ALIGNMENT PLATE-12CKT STAC64	Component		1.1943	0.075
PET ST MYLAR 0.25 X 21.78 PET NATURAL	Material		1.1943	0.075
Polyethylene terephthalate	Substance	25038-59-9	1.162	0.072975
Further Additives, not to declare	Substance	system	0.0322	0.002025

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ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	150	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
copper	e-plate Cu (electrodeposited Copper Coatings)	*Note	999,625	Yes
glass, oxide, chemicals	PS-ST GF30	*Note	320,000	Yes

*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Part Name

Exemption

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Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number Part Name Part Information	0346910121 STAC64 RA HDR 12 CKT GRY POL B TRAY						
			Haz	zardous S	Substance	S	
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
STAC64 RA H	IDR 12 CKT GRY POL B TRAY	0	0	0	0	0	0
STAC64 RA H	IDR HOUSING 12 CKT GRY POL B	0	0	0	0	0	0
0.64 X 34.93	SQ PIN BRASS REFLOW SN	0	0	0	0	0	0
0.64 X 29.86 SQ PIN BRASS REFLOW SN		0	0	0	0	0	0
PIN ALIGNMENT PLATE-12CKT STAC64		0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	MSn-RNi
Termination Base Alloy	Brass
Solder Alloy	N/A
Process Capability	WAVE

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Maximum Exposure Time (seconds)	040
Maximum Process Temperature (C)	260
Maximum Cycles at Reflow Temperature	003
J-STD-020 Moisture Sensitivity Level	N/A

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